# Resistors

### Metal Glaze<sup>™</sup> Power Pack Surface Mount High **Power Density Ceramic Package**

#### **PPS-1 Series**

- Low inductance
- 0.1Ω to 348KΩ range
- Superior surge handling capability •
- 150°C maximum operating temperature
- 1 Watt performance standard 2010 footprint •
- Flameproof ceramic package provides superior • temperature rise profile

# NOT RECOMMENDED FOR NEW DESIGNS All Pb-free parts comply with ED Directive 2011/65/EU (RoHS2)

### **Flectrical Data**

Size	Туре	Maximum Power Rating	Working Voltage <sup>1</sup>	Maximum Voltage	Resistance Range (ohms)	Tolerance (±%) <sup>2</sup>	TCR (ppm/°C)²
2010	PPS-1	1W	350	700	0.1 to 0.99	1, 2, 5	100
2010	FF3-1	IVV	350	700	1.0 to 348K	1, 2, 5	50, 100
<sup>1</sup> Not to exceed ( $\sqrt{P \times R}$ ). <sup>2</sup> Consult factory for tighter tolerances and TCRs.							

#### **Applications**

The PPS-1 will dissipate 1 watt at 70°C on a 2010 footprint. The PPS-1 is recommended for applications where board real estate or component/board TCE mismatch is a major concern. It is also recommended in circuits where a standard 2010 resistor exhibits marginal or unacceptable performance due to high power density/surge handling demands.

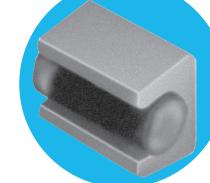
### **Environmental Data**

Characteristic	Maximum Change	Test Method
Thermal Shock	±(0.5% + 0.01 ohm)	MIL-R-55342E Par 4.7.3 (-65°C + 150°C, 5 cycles)
Low Temperature Operation	±(0.25% + 0.01 ohm)	MIL-R-55342E Par 4.7.4 (-65°C @ working voltage)
Short Time Overload	±(1.0% + 0.01 ohm)	MIL-R-55342E Par 4.7.5 (2.5 x (PxR) <sup>½</sup>
High Temperature Exposure	±(0.5% + 0.01 ohm)	MIL-R-55342E Par 4.7.6 (+150°C for 100 hours)
Resistance to Bonding Exposure	±(0.25% + 0.01 ohm)	MIL-R-55342E Par 4.7.7 (Reflow soldered to board @ 260°C for 10 seconds)
Solderability	95% minimum coverage	MIL-STD-202, Method 208 (245°C for 5 seconds)
Moisture Resistance	±(0.5% + 0.01 ohm)	MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours)
Life Test	±(1.0% + 0.01 ohm)	MIL-R-55342E Par 4.7.10 (2000 hours @ 70°C intermittent)
Terminal Adhesion Strength	±(1% + 0.01 ohm)	1200 gram push from underside of mounted chip for 60 seconds
Resistance to Board Bending	±(1% + 0.01 ohm)	Chip mounted in center of 90mm long board, deflected 5mm so as to exert pull on chip contacts for 10 seconds

#### General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print. Bi technologies <u>OIRC</u> Welwyn



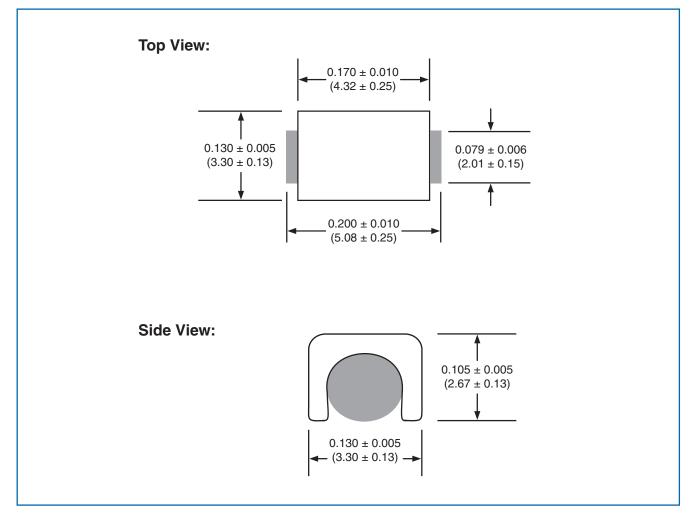


**Electro** 



# PPS-1 Series NOT RECOMMENDED FOR NEW DESIGNS

### Physical Data (Inches and (mm))



#### **General Note**

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

**Bi** technologies  $\Omega$  **IRC** Welwyn



# PPS-1 Series NOT RECOMMENDED FOR NEW DESIGNS

## **Ordering Procedure**

This product has two valid part numbers:

European (Welwyn) Part Number: PPS1-100RFI (PPS1 with TCR ±100ppm/°C at 100 ohms ±1%, Pb-free)

PPS1		100R	FI
1	2	3	4 5

1	2	3	4	5
Туре	TCR (ppm/°C)	Value	Tolerance	Termination & Packing
PPS1	Omit for ±100	E24 = 3/4 characters	F = ±1%	I = Pb-free, Tape Pack
	$-50 = \pm 50$	E96 = 4/5 characters	G = ±2%	PB = SnPb, Tape Pack
		R = ohms	J = ±5%	500/reel
		K = kilohms		

USA (IRC) Part Number: PPS11001000FLF (PPS1 with TCR ±100ppm/°C at 100 ohms ±1%, Pb-free)

PPS1	1 0 0	1000	F	LF
1	2	3	4	5

1	2 3		4	5
Туре	TCR	Value	Tolerance	Termination & Packing
PPS1	50 = ±50	3 digits + multiplier	F = ±1%	Omit for SnPb
	100 = ±100 R = ohms for		G = ±2%	LF = Pb-free
		values <100 ohms	J = ±5%	500/reel

General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.